

Title (en)
LAMINATED SOFT MAGNETIC MEMBER, SOFT MAGNETIC SHEET AND PRODUCTION METHOD FOR LAMINATED SOFT MAGNETIC MEMBER

Title (de)
LAMINIERTES WEICHMAGNETISCHES GLIED, WEICHMAGNETISCHES BLECH UND HERSTELLUNGSVERFAHREN FÜR EIN LAMINIERTES, WEICHMAGNETISCHES GLIED

Title (fr)
ELEMENT STRATIFIE CONSTITUE D'UN MATERIAU MAGNETIQUE DOUX, FEUILLE CONSTITUEE D'UN MATERIAU MAGNETIQUE DOUX ET PROCEDE DE PRODUCTION DUDIT ELEMENT STRATIFIE

Publication
EP 1426982 A4 20041117 (EN)

Application
EP 02762867 A 20020827

Priority
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Abstract (en)
[origin: EP1426982A1] A laminated soft magnetic member 5, which comprises a laminated body in which 1 μ m or less thick soft magnetic metal layer 7 and an insulating layer 6 are laminated alternately and is 0.2 mm or less in overall thickness, is excellent in permeability in the high frequency band exceeding 800 MHz, and accordingly, by being attached to a cellular phone, can improve the radiation efficiency of the electromagnetic wave on the side opposite to the head of a human body and is preferable as a member for the countermeasure against SAR. <IMAGE>

IPC 1-7
H01F 10/14; H01F 10/16; H01F 1/14; H01F 41/26; H04B 1/38; H05K 9/00; H01Q 17/00; C22C 38/00; B32B 7/12; B32B 27/06; B32B 31/20

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